

9561AGJ-VB Datasheet

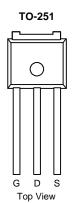
P-Channel 40 V (D-S) MOSFET

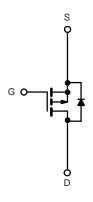
| PRODUC | RODUCT SUMMARY | | | |
|---------------------|------------------------------------|---------------------------------|--|--|
| V _{DS} (V) | R _{DS(on)} (Ω) | I _D (A) ^a | | |
| - 40 | 0.010 at V _{GS} = - 10 V | ± 55 | | |
| - 40 | 0.014 at V _{GS} = - 4.5 V | ± 54 | | |

FEATURES

Compliant to RoHS Directive 2002/95/EC







P-Channel MOSFET

| ABSOLUTE MAXIMUM RAT | INGS (T _C = 25 °C, unless oth | nerwise noted) | | | |
|--|---|-----------------------------------|-------------------|------|--|
| Parameter | | Symbol | Limit | Unit | |
| Gate-Source Voltage | | V _{GS} | ± 40 | V | |
| Continuous Drain Current $(T = 175 ^{\circ}\text{C})$ | T _C = 25 °C | | - 55 ^a | | |
| Continuous Drain Current (T _J = 175 °C) | T _C = 125 °C | I _D | - 52 | ٨ | |
| Pulsed Drain Current | | I _{DM} | - 220 | A | |
| Avalanche Current | | I _{AR} | - 60 | | |
| Repetitive Avalanche Energy ^b | L = 0.1 mH | E _{AR} | 180 | mJ | |
| Power Discinction | T _C = 25 °C | р | 45 | W | |
| Power Dissipation | T _A = 25 °C | – P _D – | 3.75 | | |
| Operating Junction and Storage Temperature Range | | T _J , T _{stg} | - 55 to 175 | °C | |

| THERMAL RESISTANCE | THERMAL RESISTANCE RATINGS | | | | | |
|---------------------|---------------------------------|---------------------|-------|------|--|--|
| Parameter | | Symbol | Limit | Unit | | |
| Junction-to-Ambient | PCB Mount (TO-263) ^c | Р | 40 | | | |
| Junction-to-Ambient | Free Air (TO-220AB) | – R _{thJA} | 62.5 | °C/W | | |
| Junction-to-Case | | R _{thJC} | 0.8 | | | |

Notes:

a. Package limited.

b. Duty cycle \leq 1 %.

c. When mounted on 1" square PCB (FR-4 material).

d. See SOA curve for voltage derating.

* Pb containing terminations are not RoHS compliant, exemptions may apply.



| SPECIFICATIONS ($T_J = 25$ | °C, unless o | otherwise noted) | | | | | |
|---|---------------------------|--|--------|-------|-------|------|--|
| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit | |
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{GS} = 0 V, I_{D} = -250 \mu A$ | - 40 | | | V | |
| Gate Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$ | - 1.0 | | - 2.5 | v | |
| Gate-Body Leakage | I _{GSS} | $V_{DS} = 0 V, V_{GS} = \pm 20 V$ | | | ± 100 | nA | |
| | | $V_{DS} = -40 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$ | | | - 1 | | |
| Zero Gate Voltage Drain Current | I _{DSS} | $V_{DS} = -40 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$ | | | - 50 | μA | |
| | | $V_{DS} = -40 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$ | | | - 250 | | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} = -5 V, V_{GS} = -10 V$ | - 120 | | | А | |
| | | V _{GS} = - 10 V, I _D = - 30 A | | 0.010 | | | |
| Drain-Source On-State Resistance ^a | Б | V _{GS} = - 10 V, I _D = - 30 A, T _J = 125 °C | | 0.016 | | Ω | |
| Dialin-Source On-State Resistance | R _{DS(on)} | V _{GS} = - 10 V, I _D = - 30 A, T _J = 175 °C | | 0.023 | | | |
| | | V _{GS} = - 4.5 V, I _D = - 20 A | | 0.014 | | | |
| Forward Transconductance ^a | 9 _{fs} | V _{DS} = - 15 V, I _D = - 75 A | 20 | | | S | |
| Dynamic ^b | | · · · · | | | | | |
| Input Capacitance | C _{iss} | | | 3000 | | | |
| Output Capacitance | C _{oss} | $V_{GS} = 0 V, V_{DS} = -25 V, f = 1 MHz$ | | 620 | | pF | |
| Reversen Transfer Capacitance | C _{rss} | | | 315 | | 1 | |
| Total Gate Charge ^c | Qg | | | 160 | | | |
| Gate-Source Charge ^c | Q _{gs} | V_{DS} = - 15 V, V_{GS} = - 10 V, I_{D} = - 75 A | 5 A 32 | | | nC | |
| Gate-Drain Charge ^c | Q _{gd} | <u>~</u> | | 30 | | 1 | |
| Turn-On Delay Time ^c | t _{d(on)} | | | 25 | 40 | | |
| Rise Time ^c | t _r | V _{DD} = - 15 V, R _I = 0.2 Ω | | 225 | 360 | | |
| Turn-Off Delay Time ^c | t _{d(off)} | $I_D \cong$ - 75 Å, V_{GEN} = - 10 V, R_g = 2.5 Ω | | 150 | 240 | ns | |
| Fall Time ^c | t _f | | | 210 | 340 | | |
| Source-Drain Diode Ratings and Cha | racteristics ^b | (T _C = 25 °C) | | | | | |
| Continuous Current | ا _S | | | - 220 | | • | |
| Pulsed Current | I _{SM} | | | | - 240 | A | |
| Forward Voltage ^a | V _{SD} | I _F = - 75 A, V _{GS} = 0 V | | - 1.2 | - 1.5 | V | |
| Reverse Recovery Time | t _{rr} | | | 55 | 100 | ns | |
| Peak Reverse Recovery Current | I _{RM(REC)} | I _F = - 75 A, dl/dt = 100 A/μs | | 2.5 | 5 | А | |
| Reverse Recovery Charge | Q _{rr} | 1 1 | | 0.07 | 0.25 | μC | |

Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

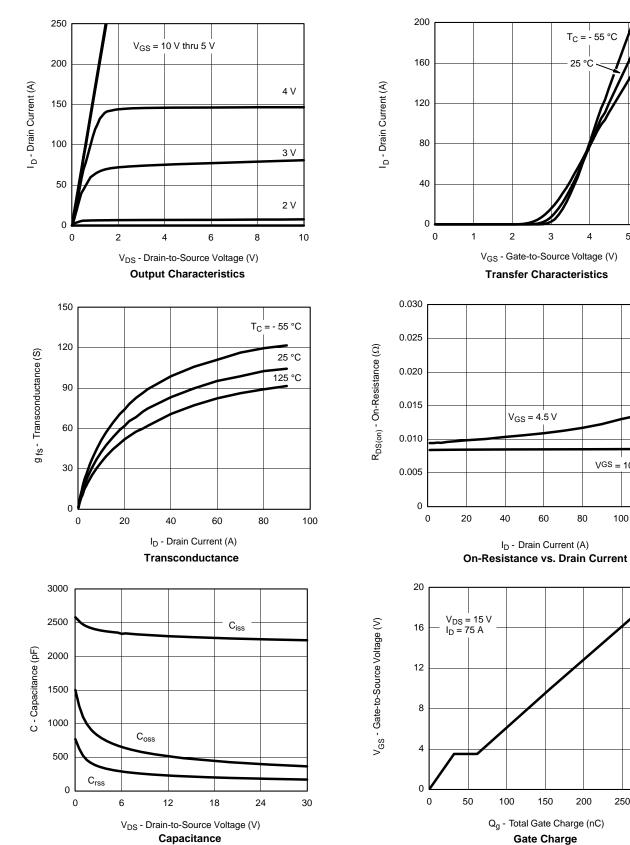


125 °C

VGS = 10 V

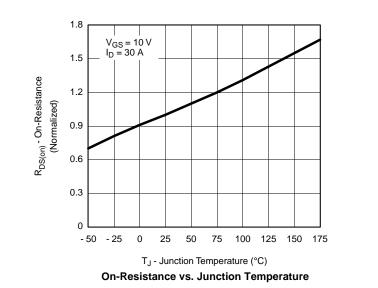
T_C = - 55 °C

°C

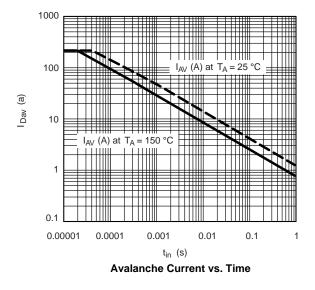


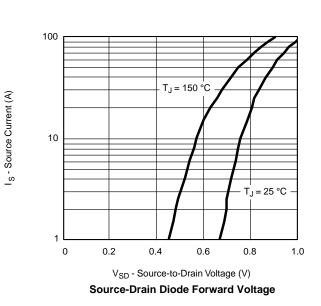
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

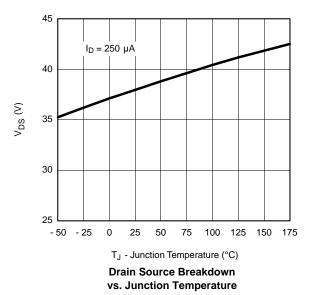




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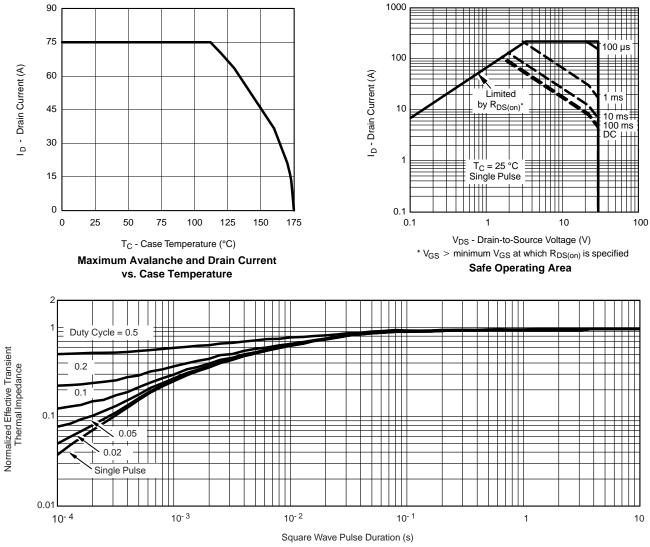








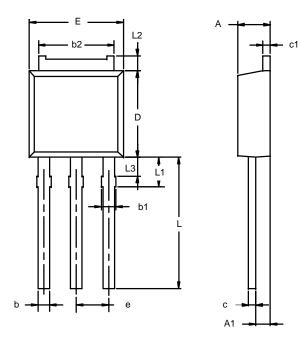
THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Case



TO-251AA (DPAK)



Note: Dimension L3 is for reference only.

| | MILLIN | IETERS | INCHES | | |
|---------------------|--------------------|-------------|-----------|-------|--|
| Dim | Min | Мах | Min | Max | |
| Α | 2.21 | 2.38 | 0.087 | 0.094 | |
| A1 | 0.89 | 1.14 | 0.035 | 0.045 | |
| b | 0.71 | 0.89 | 0.028 | 0.035 | |
| b1 | 0.76 | 1.14 | 0.030 | 0.045 | |
| b2 | 5.23 | 5.43 | 0.206 | 0.214 | |
| С | 0.46 | 0.58 | 0.018 | 0.023 | |
| c1 | 0.46 | 0.58 | 0.018 | 0.023 | |
| D | 5.97 | 6.22 | 0.235 | 0.245 | |
| Е | 6.48 | 6.73 | 0.255 | 0.265 | |
| е | 2.28 | BSC | 0.090 BSC | | |
| L | 8.89 | 9.53 | 0.350 | 0.375 | |
| L1 | 1.91 | 2.28 | 0.075 | 0.090 | |
| L2 | 0.89 | 1.27 | 0.035 | 0.050 | |
| L3 | 1.15 | 1.52 | 0.045 | 0.060 | |
| ECN: S-0 DWG: 53 | 3946—Rev. E 346 | , 09-Jul-01 | | | |



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